DS90UR124 TIDA-00136

ltem	Qty Reference	Part	PCB Footprint	Comments	MFR	MFR Part#	Digi-Key Part#	Lead Free?	RoHS Compliant?
	0. 01 00 057	0.4.5			Desservia		DOCODOROT ND	VEO	VEO
1	3 C1,C2,C57	0.1uF	CAP/HDC-0603	CAP CERAMIC .1UF 50V X7R 0603 CAPACITOR TANT 2.2UF 20V 10% SMD	Panasonic KEMET	ECJ-1VB1H104K	PCC2398CT-ND 399-3714-1-ND	YES	YES
3	1 C4	2.2uF	3528-21_EIA			T491B225K020AT		YES	YES YES
4	1 C5	22uF	CAP/N	CAP TANTALUM 22UF 25V 20% SMD	nichicon	F931E226MNC	493-2391-1-ND	YES YES	YES
5	1 C6	0.1uF	CAP/HDC-1206	CAP .10UF 50V CERAMIC X7R 1206	KEMET	C1206C104K5RACTU	399-1249-1-ND		
6	8 C32,C33,C34,C41,C47,C50, C53,C54	22uF	CAP/EIA-B 3528-21	CAPACITOR TANT 22UF 16V 20% SMD	Kemet	T494B226M016AT	399-3835-1-ND	YES	YES
7	8 C35,C38,C40,C43,C46,C48, C52,C55	0.1uF	CAP/HDC-0603	CAP .1UF ±10% 25V CERAMIC X7R 0603	Panasonic	ECJ-1VB1E104K	PCC2277CT-ND	YES	YES
8	8 C36,C37,C39,C44,C45,C49, C51,C56	0.01uF	CAP/HDC-0603	CAP CERAMIC .01UF 100V X7R 0603	KEMET	C0603C103K1RACTU	399-3189-1-ND	YES	YES
9	2 JP2,JP1	3-Pin Header	Header/3P	CONN HEADER VERT .100 3POS 15AU	AMP/Tyco	87224-3	A26545-ND	YES	YES
13	1 J2	mini USB 5pin	mini_USB_surface_mount	CONN RECEPT MINI USB 2.0 5POS.	Hirose	UX60-MB-5ST	H2959CT-ND	YES	YES
14	1 J3	IDC2X25_Unshrouded	IDC-50	CONN HEADER 50POS .100 VERT GOLD UNSHROUDED	MOLEX	10-89-7502	WM26850-ND	YES	YES
15	2 J4,J5	BANANA	CON/BANANA-S	BANANA-female (non-insulated)	Johnson	108-0740-001	J147-ND	YES	YES
17	1 LED1	0402_orange_LED	0402	LED ORN/CLEAR 610NM 0402 SMD	Lumex Opto/Components Inc	SML-LX0402SOC-TR	67-1879-1-ND	YES	YES
18	1 LED2	0603_green_LED	0603 (Super Thin)	LED GREEN CLEAR THIN 0603 SMD	LITE-ON INC	LTST-C191KGKT	160-1446-1-ND	YES	YES
19	2 R40,R1	49.9ohm	RES/HDC-0201	RES 0.0 OHM 1/20W 5% 0201 SMD	Panasonic	ERJ-1GE0R00C	P0.0AGCT-ND	YES	YES
20	9 R2,R3,R4,R34,R35,R36,R37, R38,R39	10K	RES/HDC-0805	1% Precision Thick Film Chip Res; 1/10W	Panasonic	ERJ-6ENF1002	P10.0KCCT-ND	YES	YES
22	9 R9,R10,R11,R12,R13,R14, R15,R16,R21	0 Ohm,0402	RES/HDC-0402	RES ZERO OHM 1/16W 5% 0402 SMD	Panasonic	ERJ-2GEJ0R00X	P0.0JTR-ND	YES	YES
23	1 S1	SW DIP-3	DIP-6	SWITCH DIP EXTENDED SEALED 3POS	Grayhill	78B03ST	GH7182-ND	YES	YES
24	1 S2	SW DIP-6	DIP-12	SWITCH DIP EXTENDED SEALED 6POS	Grayhill	78B06ST	GH7188-ND	YES	YES
26	1 U1	DS90UR124	64 pin TQFP	DS90UR124 Rx Deserializer	ті	DS90UR124QVS	DS90UR124QVS/NOPB-ND	YES	YES

61 actual components to be stuffed

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